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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Sion C. Quinlan et al.

Attorney Docket No.: 30022/US/2

Filed : concurrently herewith

Title : SEMICONDUCTOR PACKAGE ASSEMBLY AND METHOD FOR ELECTRICALLY ISOLATING MODULES

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97 through 1.98, applicant wishes to make known to the Patent and Trademark Office the references set forth on the attached form PTO-1449. This application relies, under 35 U.S.C. § 120, on the earlier filing date of prior Application No. 10/057,205, filed January 25, 2002. The references listed on the attached Form PTO-1449 are enclosed as required under 37 C.F.R. § 1.98. Although the aforesaid references are made known to the Patent and Trademark Office in compliance with applicants' duty to disclose all information they are aware of which is believed relevant to the examination of the above-identified application, applicants believe that their invention is patentable.

Please acknowledge receipt of this Information Disclosure Statement and kindly make the cited references of record in the above-identified application.

Respectfully submitted,

DORSEY & WHITNEY LLP

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Enclosures:
Postcard
Form PTO-1449
Cited References (31)

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FORM PTO-1449 (REV.7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 30022/US/2	APPLICATION NO. Not Yet Assigned
INFORMATION DISCLOSURE STATEMENT *(Use several sheets if necessary)*		APPLICANT(S) Sion C. Quinlan and Tim J. Bales	
		FILING DATE Concurrently Herewith	GROUP ART UNIT Not Yet Assigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	5,975,958	11-02-99	Weidler	439	620	
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							YES	NO
	AH	00/45420	08/03/00	WO				
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